



Welcome to [E-XFL.COM](#)

### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	CANbus, I <sup>2</sup> C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev64gm104t-i-pt">https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev64gm104t-i-pt</a>

## 4.5.3 MODULO ADDRESSING APPLICABILITY

Modulo Addressing can be applied to the Effective Address (EA) calculation associated with any W register. Address boundaries check for addresses equal to:

- The upper boundary addresses for incrementing buffers
- The lower boundary addresses for decrementing buffers

The address boundaries check for addresses less than or greater than the upper (for incrementing buffers) and lower (for decrementing buffers) boundary addresses (not just equal to). Address changes can, therefore, jump beyond boundaries and still be adjusted correctly.

**Note:** The modulo corrected Effective Address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the Effective Address. When an address offset, such as [W7 + W2] is used, Modulo Addressing correction is performed, but the contents of the register remain unchanged.

## 4.6 Bit-Reversed Addressing

Bit-Reversed Addressing mode is intended to simplify data reordering for radix-2 FFT algorithms. It is supported by the X AGU for data writes only.

The modifier, which can be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order. Thus, the only operand requiring reversal is the modifier.

### 4.6.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing mode is enabled when all of these conditions are met:

- BWM<3:0> bits (W register selection) in the MODCON register are any value other than '1111' (the stack cannot be accessed using Bit-Reversed Addressing)
- The BREN bit is set in the XBREV register
- The addressing mode used is Register Indirect with Pre-Increment or Post-Increment

If the length of a bit-reversed buffer is  $M = 2^N$  bytes, the last 'N' bits of the data buffer start address must be zeros.

XB<14:0> is the Bit-Reversed Addressing modifier, or 'pivot point', which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

**Note:** All bit-reversed EA calculations assume word-sized data (LSb of every EA is always clear). The XB value is scaled accordingly to generate compatible (byte) addresses.

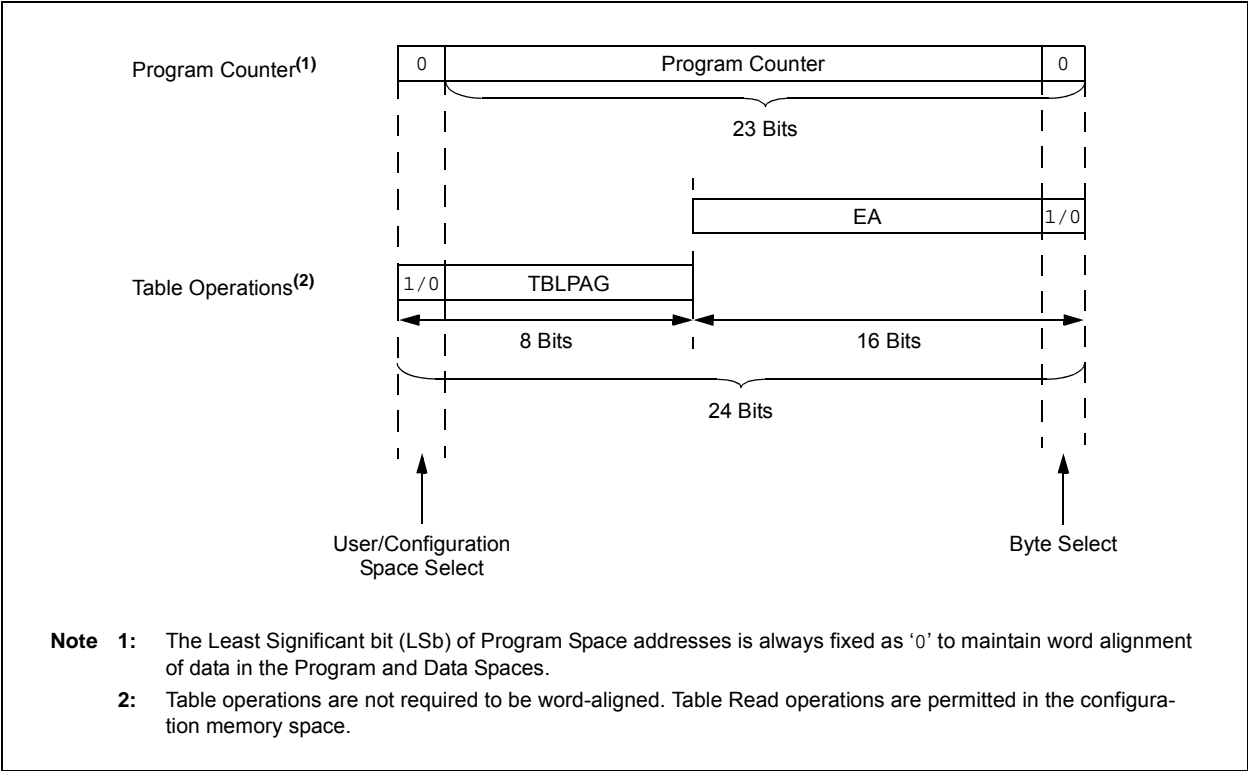
When enabled, Bit-Reversed Addressing is executed only for Register Indirect with Pre-Increment or Post-Increment Addressing and word-sized data writes. It does not function for any other addressing mode or for byte-sized data and normal addresses are generated instead. When Bit-Reversed Addressing is active, the W Address Pointer is always added to the address modifier (XB) and the offset associated with the Register Indirect Addressing mode is ignored. In addition, as word-sized data is a requirement, the LSb of the EA is ignored (and always clear).

**Note:** Modulo Addressing and Bit-Reversed Addressing can be enabled simultaneously using the same W register, but Bit-Reversed Addressing operation will always take precedence for data writes when enabled.

If Bit-Reversed Addressing has already been enabled by setting the BREN (XBREV<15>) bit, a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the Bit-Reversed Pointer.

The operation of Bit-Reversed Addressing is shown in Figure 4-16 and Table 4-46.

FIGURE 4-17: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



# dsPIC33EVXXXGM00X/10X FAMILY

## REGISTER 9-4: OSCTUN: FRC OSCILLATOR TUNING REGISTER<sup>(1)</sup>

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TUN<5:0>					
bit 7							bit 0

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5-0 **TUN<5:0>:** FRC Oscillator Tuning bits

111111 = Center frequency – 0.048% (7.363 MHz)

•

•

•

100001 = Center frequency – 1.5% (7.259 MHz)

100000 = Center frequency – 1.548% (7.2552 MHz)

011111 = Center frequency + 1.5% (7.48 MHz)

011110 = Center frequency + 1.452% (7.477 MHz)

•

•

•

000001 = Center frequency + 0.048% (7.373 MHz)

000000 = Center frequency (7.37 MHz nominal)

**Note 1:** This register is reset only on a Power-on Reset (POR).

# dsPIC33EVXXXGM00X/10X FAMILY

**TABLE 11-2: INPUT PIN SELECTION FOR SELECTABLE INPUT SOURCES**

Peripheral Pin Select Input Register Value	Input/Output	Pin Assignment	Peripheral Pin Select Input Register Value	Input/Output	Pin Assignment
000 0000	I	Vss	011 0010	I	RPI50
000 0001	I	CMP1 <sup>(1)</sup>	011 0011	I	RPI51
000 0010	I	CMP2 <sup>(1)</sup>	011 0100	I	RPI52
000 0011	I	CMP3 <sup>(1)</sup>	011 0101	I	RPI53
000 0100	I	CMP4 <sup>(1)</sup>	011 0110	I/O	RP54
000 0101	—	—	011 0111	I/O	RP55
000 1100	I	CMP5 <sup>(1)</sup>	011 1000	I/O	RP56
000 1101	—	—	011 1001	I/O	RP57
000 1110	—	—	011 1010	I	RPI58
000 1111	—	—	011 1011	—	—
001 0000	I	RPI16	011 1100	I	RPI60
001 0001	I	RPI17	011 1101	I	RPI61
001 0010	I	RPI18	011 1110	—	—
001 0011	I	RPI19	011 1111	I	RPI 63
001 0100	I/O	RP20	100 0000	—	—
001 0101	—	—	100 0001	—	—
001 0110	—	—	100 0010	—	—
001 0111	—	—	100 0011	—	—
001 1000	I	RPI24	100 0100	—	—
001 1001	I	RPI25	100 0101	I/O	RP69
001 1010	—	—	100 0110	I/O	RP70
001 1011	I	RPI27	100 0111	—	—
001 1100	I	RPI28	100 1000	I	RPI72
001 1101	—	—	100 1001	—	—
001 1110	—	—	100 1010	—	—
001 1111	—	—	100 1011	—	—
010 0000	I	RPI32	100 1110	—	—
010 0001	I	RPI33	100 1111	—	—
010 0010	I	RPI34	101 0010	—	—
010 0011	I/O	RP35	101 0011	—	—
010 0100	I/O	RP36	101 0100	—	—
010 0101	I/O	RP37	010 1001	I/O	RP41
010 0110	I/O	RP38	010 1010	I/O	RP42
010 0111	I/O	RP39	010 1011	I/O	RP43
010 1000	I/O	RP40	101 1000	—	—
010 1100	I	RPI44	101 1001	—	—
010 1101	I	RPI45	101 1010	—	—
010 1110	I	RPI46	101 1011	—	—
010 1111	I	RPI47	101 1100	—	—
011 0000	I/O	RP48	101 1101	—	—

**Legend:** Shaded rows indicate the PPS Input register values that are unimplemented.

**Note 1:** These are virtual pins. See **Section 11.5.4.1 “Virtual Connections”** for more information on selecting this pin assignment.

# dsPIC33EVXXXGM00X/10X FAMILY

## REGISTER 11-26: RPOR8: PERIPHERAL PIN SELECT OUTPUT REGISTER 8<sup>(1)</sup>

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP70R5	RP70R4	RP70R3	RP70R2	RP70R1	RP70R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP69R5	RP69R4	RP69R3	RP69R2	RP69R1	RP69R0
bit 7							bit 0

### Legend:

R = Readable bit                      W = Writable bit                      U = Unimplemented bit, read as '0'  
-n = Value at POR                      '1' = Bit is set                      '0' = Bit is cleared                      x = Bit is unknown

bit 15-14                      **Unimplemented:** Read as '0'

bit 13-8                      **RP70R<5:0>:** Peripheral Output Function is Assigned to RP70 Output Pin bits  
(see Table 11-3 for peripheral function numbers)

bit 7-6                      **Unimplemented:** Read as '0'

bit 5-0                      **RP69R<5:0>:** Peripheral Output Function is Assigned to RP69 Output Pin bits  
(see Table 11-3 for peripheral function numbers)

**Note 1:** This register is present in dsPIC33EVXXXGM004/104/006/106 devices only.

## REGISTER 11-27: RPOR9: PERIPHERAL PIN SELECT OUTPUT REGISTER 9<sup>(1)</sup>

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP118R5	RP118R4	RP118R3	RP118R2	RP118R1	RP118R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP97R5	RP97R4	RP97R3	RP97R2	RP97R1	RP97R0
bit 7							bit 0

### Legend:

R = Readable bit                      W = Writable bit                      U = Unimplemented bit, read as '0'  
-n = Value at POR                      '1' = Bit is set                      '0' = Bit is cleared                      x = Bit is unknown

bit 15-14                      **Unimplemented:** Read as '0'

bit 13-8                      **RP118R<5:0>:** Peripheral Output Function is Assigned to RP118 Output Pin bits  
(see Table 11-3 for peripheral function numbers)

bit 7-6                      **Unimplemented:** Read as '0'

bit 5-0                      **RP97R<5:0>:** Peripheral Output Function is Assigned to RP97 Output Pin bits  
(see Table 11-3 for peripheral function numbers)

**Note 1:** This register is present in dsPIC33EVXXXGM004/106 devices only.

# dsPIC33EVXXXGM00X/10X FAMILY

## 15.1 Input Capture Control Registers

**REGISTER 15-1: ICxCON1: INPUT CAPTURE x CONTROL REGISTER 1**

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
—	—	ICSIDL	ICTSEL2	ICTSEL1	ICTSEL0	—	—
bit 15						bit 8	

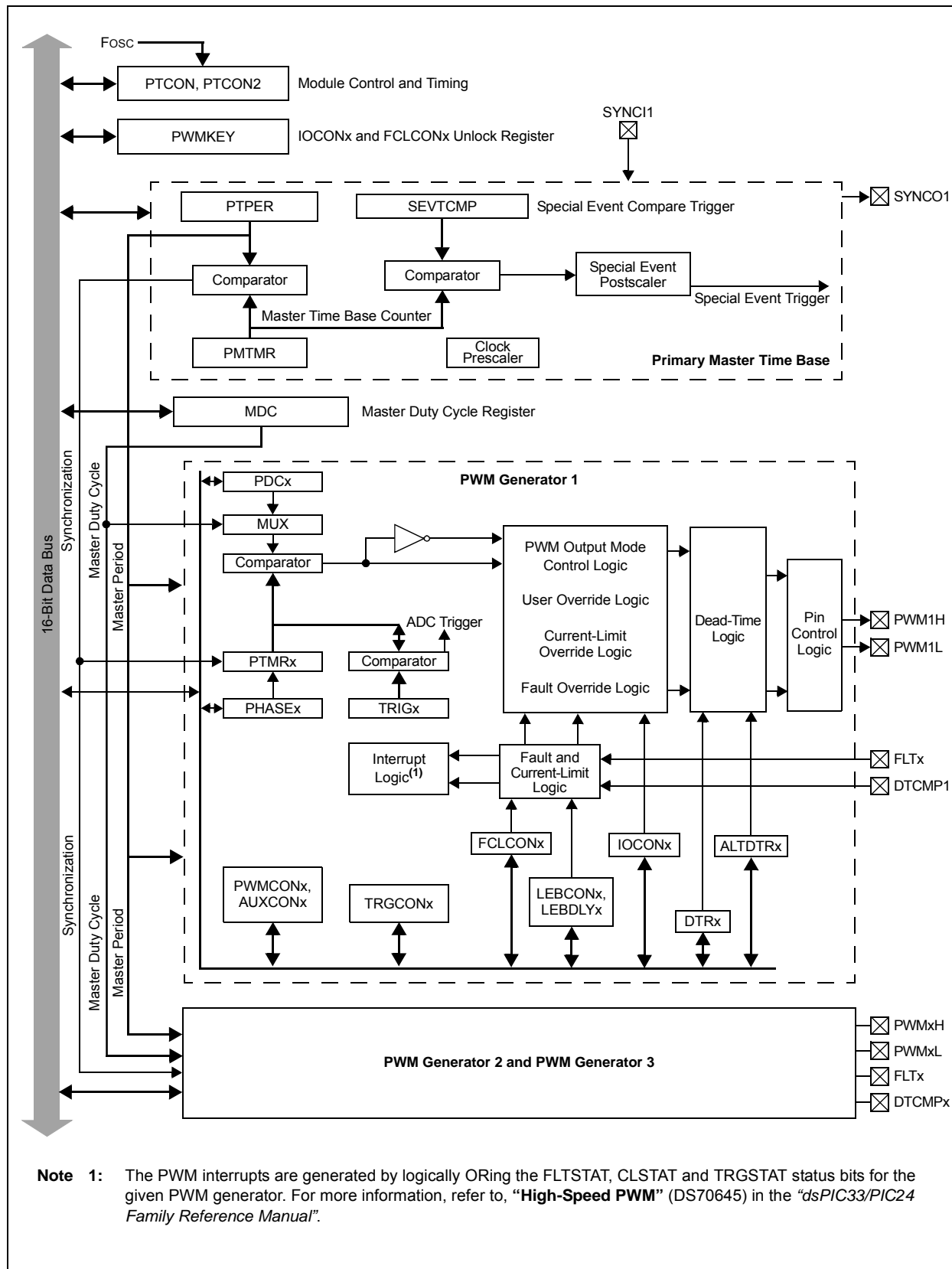
U-0	R/W-0	R/W-0	R-0, HC, HS	R-0, HC, HS	R/W-0	R/W-0	R/W-0
—	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0
bit 7						bit 0	

<b>Legend:</b>	HC = Hardware Clearable bit	HS = Hardware Settable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared
		x = Bit is unknown

- bit 15-14      **Unimplemented:** Read as '0'
- bit 13      **ICSIDL:** Input Capture x Stop in Idle Mode Control bit  
1 = Input Capture x will halt in CPU Idle mode  
0 = Input Capture x will continue to operate in CPU Idle mode
- bit 12-10      **ICTSEL<2:0>:** Input Capture x Timer Select bits  
111 = Peripheral clock (FP) is the clock source of the ICx  
110 = Reserved  
101 = Reserved  
100 = T1CLK is the clock source of the ICx (only the synchronous clock is supported)  
011 = T5CLK is the clock source of the ICx  
010 = T4CLK is the clock source of the ICx  
001 = T2CLK is the clock source of the ICx  
000 = T3CLK is the clock source of the ICx
- bit 9-7      **Unimplemented:** Read as '0'
- bit 6-5      **ICI<1:0>:** Number of Captures per Interrupt Select bits (this field is not used if ICM<2:0> = 001 or 111)  
11 = Interrupt on every fourth capture event  
10 = Interrupt on every third capture event  
01 = Interrupt on every second capture event  
00 = Interrupt on every capture event
- bit 4      **ICOV:** Input Capture x Overflow Status Flag bit (read-only)  
1 = Input Capture x buffer overflow has occurred  
0 = Input Capture x buffer overflow has not occurred
- bit 3      **ICBNE:** Input Capture x Buffer Not Empty Status bit (read-only)  
1 = Input Capture x buffer is not empty, at least one more capture value can be read  
0 = Input Capture x buffer is empty
- bit 2-0      **ICM<2:0>:** Input Capture x Mode Select bits  
111 = Input Capture x functions as an interrupt pin only in CPU Sleep and Idle modes (rising edge detect only, all other control bits are not applicable)  
110 = Unused (module is disabled)  
101 = Capture mode, every 16th rising edge (Prescaler Capture mode)  
100 = Capture mode, every 4th rising edge (Prescaler Capture mode)  
011 = Capture mode, every rising edge (Simple Capture mode)  
010 = Capture mode, every falling edge (Simple Capture mode)  
001 = Capture mode, every edge, rising and falling (Edge Detect mode (ICI<1:0>) is not used in this mode)  
000 = Input Capture x module is turned off

# dsPIC33EVXXXGM00X/10X FAMILY

**FIGURE 17-2: HIGH-SPEED PWMx MODULE REGISTER INTERCONNECTION DIAGRAM**





# dsPIC33EVXXXGM00X/10X FAMILY

---

NOTES:

## 18.0 SERIAL PERIPHERAL INTERFACE (SPI)

**Note 1:** This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**Serial Peripheral Interface (SPI)**” (DS70005185) in the “dsPIC33/PIC24 Family Reference Manual”, which is available from the Microchip web site ([www.microchip.com](http://www.microchip.com)).

**2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Serial Peripheral Interface (SPI) module is a synchronous serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices can be serial EEPROMs, shift registers, display drivers, ADC Converters, etc. The SPI module is compatible with the Motorola® SPI and SIOP interfaces.

The dsPIC33EVXXXGM00X/10X device family offers two SPI modules on a single device, SPI1 and SPI2, that are functionally identical. Each SPI module includes an eight-word FIFO buffer and allows DMA bus connections. When using the SPI module with DMA, FIFO operation can be disabled.

**Note:** In this section, the SPI modules are referred to together as SPIx, or separately as SPI1 and SPI2. Special Function Registers follow a similar notation. For example, SPIxCON refers to the control register for the SPI1 and SPI2 modules.

The SPI1 module uses dedicated pins which allow for a higher speed when using SPI1. The SPI2 module takes advantage of the Peripheral Pin Select (PPS) feature to allow for greater flexibility in pin configuration of this module, but results in a lower maximum speed. See **Section 30.0 “Electrical Characteristics”** for more information.

The SPIx serial interface consists of the following four pins:

- SDIx: Serial Data Input
- SDOx: Serial Data Output
- SCKx: Shift Clock Input or Output
- SSx/FSYNCx: Active-Low Slave Select or Frame Synchronization I/O Pulse

**Note:** All of the 4 pins of the SPIx serial interface must be configured as digital in the ANSELx registers.

The SPIx module can be configured to operate with two, three or four pins. In 3-pin mode, SSx is not used. In 2-pin mode, neither SDOx nor SSx is used.

Figure 18-1 illustrates the block diagram of the SPIx module in Standard and Enhanced modes.

# dsPIC33EVXXXGM00X/10X FAMILY

---

## REGISTER 21-2: UxSTA: UARTx STATUS AND CONTROL REGISTER (CONTINUED)

- bit 5      **ADDEN**: Address Character Detect bit (bit 8 of received data = 1)  
1 = Address Detect mode is enabled; if 9-bit mode is not selected, this does not take effect  
0 = Address Detect mode is disabled
- bit 4      **RIDLE**: Receiver Idle bit (read-only)  
1 = Receiver is Idle  
0 = Receiver is active
- bit 3      **PERR**: Parity Error Status bit (read-only)  
1 = Parity error has been detected for the current character (character at the top of the receive FIFO)  
0 = Parity error has not been detected
- bit 2      **FERR**: Framing Error Status bit (read-only)  
1 = Framing error has been detected for the current character (character at the top of the receive FIFO)  
0 = Framing error has not been detected
- bit 1      **OERR**: Receive Buffer Overrun Error Status bit (clear/read-only)  
1 = Receive buffer has overflowed  
0 = Receive buffer has not overflowed; clearing a previously set OERR bit (1 → 0 transition) resets the receive buffer and the UxRSR to the empty state
- bit 0      **URXDA**: UARTx Receive Buffer Data Available bit (read-only)  
1 = Receive buffer has data, at least one more character can be read  
0 = Receive buffer is empty

**Note 1:** Refer to “**Universal Asynchronous Receiver Transmitter (UART)**” (DS70000582) in the “*dsPIC33/PIC24 Family Reference Manual*” for information on enabling the UART module for transmit operation.

## 24.3 ADC Control Registers

**REGISTER 24-1: ADxCON1: ADCx CONTROL REGISTER 1**

R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM1	FORM0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0, HC, HS	R/C-0, HC, HS
SSRC2	SSRC1	SSRC0	SSRCG	SIMSAM	ASAM	SAMP	DONE <sup>(1)</sup>
bit 7							bit 0

<b>Legend:</b>	C = Clearable bit	U = Unimplemented bit, read as '0'
R = Readable bit	W = Writable bit	HS = Hardware Settable bit    HC = Hardware Clearable bit
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared            x = Bit is unknown

- bit 15      **ADON:** ADCx Operating Mode bit  
1 = ADCx module is operating  
0 = ADCx is off
- bit 14      **Unimplemented:** Read as '0'
- bit 13      **ADSIDL:** ADCx Stop in Idle Mode bit  
1 = Discontinues module operation when the device enters Idle mode  
0 = Continues module operation in Idle mode
- bit 12      **ADDMABM:** ADCx DMA Buffer Build Mode bit  
1 = DMA buffers are written in the order of conversion; the module provides an address to the DMA channel that is the same as the address used for the non-DMA stand-alone buffer  
0 = DMA buffers are written in Scatter/Gather mode; the module provides a Scatter/Gather mode address to the DMA channel based on the index of the analog input and the size of the DMA buffer
- bit 11      **Unimplemented:** Read as '0'
- bit 10      **AD12B:** ADCx 10-Bit or 12-Bit Operation Mode bit  
1 = 12-bit, 1-channel ADC operation  
0 = 10-bit, 4-channel ADC operation
- bit 9-8      **FORM<1:0>:** Data Output Format bits  
For 10-Bit Operation:  
11 = Signed fractional (DOUT = sddd dddd dd00 0000, where s = .NOT.d<9>)  
10 = Fractional (DOUT = dddd dddd dd00 0000)  
01 = Signed integer (DOUT = ssss sssd dddd dddd, where s = .NOT.d<9>)  
00 = Integer (DOUT = 0000 00dd dddd dddd)  
For 12-Bit Operation:  
11 = Signed fractional (DOUT = sddd dddd dddd 0000, where s = .NOT.d<11>)  
10 = Fractional (DOUT = dddd dddd dddd 0000)  
01 = Signed integer (DOUT = ssss sddd dddd dddd, where s = .NOT.d<11>)  
00 = Integer (DOUT = 0000 dddd dddd dddd)

**Note 1:** Do not clear the DONE bit in software if auto-sample is enabled (ASAM = 1).

# dsPIC33EVXXXGM00X/10X FAMILY

**REGISTER 24-2: ADxCON2: ADCx CONTROL REGISTER 2**

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
VCFG2 <sup>(1)</sup>	VCFG1 <sup>(1)</sup>	VCFG0 <sup>(1)</sup>	—	—	CSCNA	CHPS1	CHPS0
bit 15						bit 8	

R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BUFS	SMPI4	SMPI3	SMPI2	SMPI1	SMPI0	BUFM	ALTS
bit 7						bit 0	

**Legend:**

R = Readable bit      W = Writable bit      U = Unimplemented bit, read as '0'  
 -n = Value at POR      '1' = Bit is set      '0' = Bit is cleared      x = Bit is unknown

bit 15-13 **VCFG<2:0>: Converter Voltage Reference Configuration bits<sup>(1)</sup>**

Value	VREFH	VREFL
xxx	AVDD	AVSS

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **CSCNA:** Input Scan Select bit

1 = Scans inputs for CH0+ during Sample MUX A  
 0 = Does not scan inputs

bit 9-8 **CHPS<1:0>: Channel Select bits**

In 12-Bit Mode (AD21B = 1), CHPS<1:0> bits are Unimplemented and are Read as '0':

1x = Converts CH0, CH1, CH2 and CH3  
 01 = Converts CH0 and CH1  
 00 = Converts CH0

bit 7 **BUFS:** Buffer Fill Status bit (only valid when BUFM = 1)

1 = ADCx is currently filling the second half of the buffer; the user application should access data in the first half of the buffer  
 0 = ADCx is currently filling the first half of the buffer; the user application should access data in the second half of the buffer

bit 6-2 **SMPI<4:0>: Increment Rate bits**

When ADDMAEN = 0:

x1111 = Generates interrupt after completion of every 16th sample/conversion operation  
 x1110 = Generates interrupt after completion of every 15th sample/conversion operation

•  
•  
•

x0001 = Generates interrupt after completion of every 2nd sample/conversion operation  
 x0000 = Generates interrupt after completion of every sample/conversion operation

When ADDMAEN = 1:

11111 = Increments the DMA address after completion of every 32nd sample/conversion operation  
 11110 = Increments the DMA address after completion of every 31st sample/conversion operation

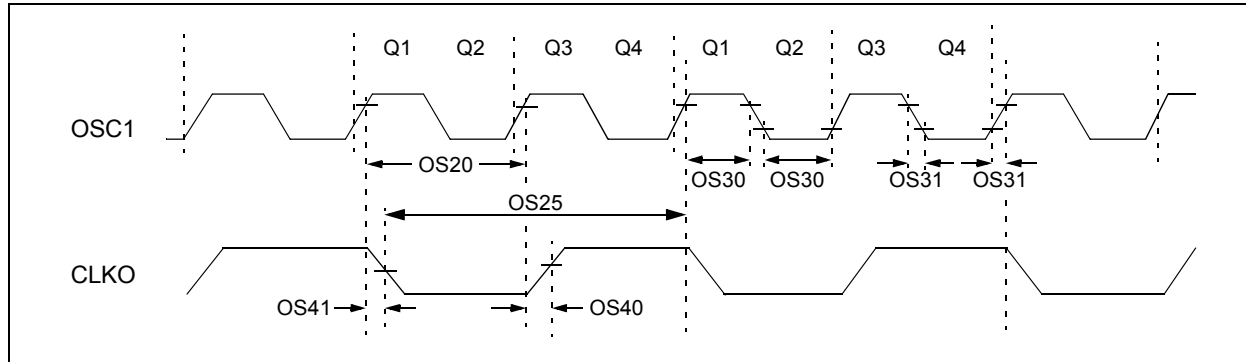
•  
•  
•

00001 = Increments the DMA address after completion of every 2nd sample/conversion operation  
 00000 = Increments the DMA address after completion of every sample/conversion operation

**Note 1:** The ADCx VREFH Input is connected to AVDD and the VREFL input is connected to AVSS.

# dsPIC33EVXXXGM00X/10X FAMILY

**FIGURE 30-2: EXTERNAL CLOCK TIMING**



**TABLE 30-17: EXTERNAL CLOCK TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Sym	Characteristic	Min.	Typ. <sup>(1)</sup>	Max.	Units	Conditions
OS10	FIN	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC	—	40	MHz	EC
		Oscillator Crystal Frequency	3.5 10	— —	10 25	MHz MHz	XT HS
OS20	Tosc	Tosc = 1/Fosc	12.5	—	DC	ns	TA = +125°C
OS25	Tcy	Instruction Cycle Time <sup>(2)</sup>	25	—	DC	ns	TA = +125°C
OS30	TosL, TosH	External Clock in (OSC1) High or Low Time	0.375 x Tsc	—	0.625 x Tsc	ns	EC
OS31	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	20	ns	EC
OS40	TckR	CLKO Rise Time <sup>(3)</sup>	—	5.2	—	ns	
OS41	TckF	CLKO Fall Time <sup>(3)</sup>	—	5.2	—	ns	
OS42	GM	External Oscillator Transconductance <sup>(4)</sup>	—	12	—	mA/V	HS, VDD = 5.0V, TA = +25°C
			—	6	—	mA/V	XT, VDD = 5.0V, TA = +25°C

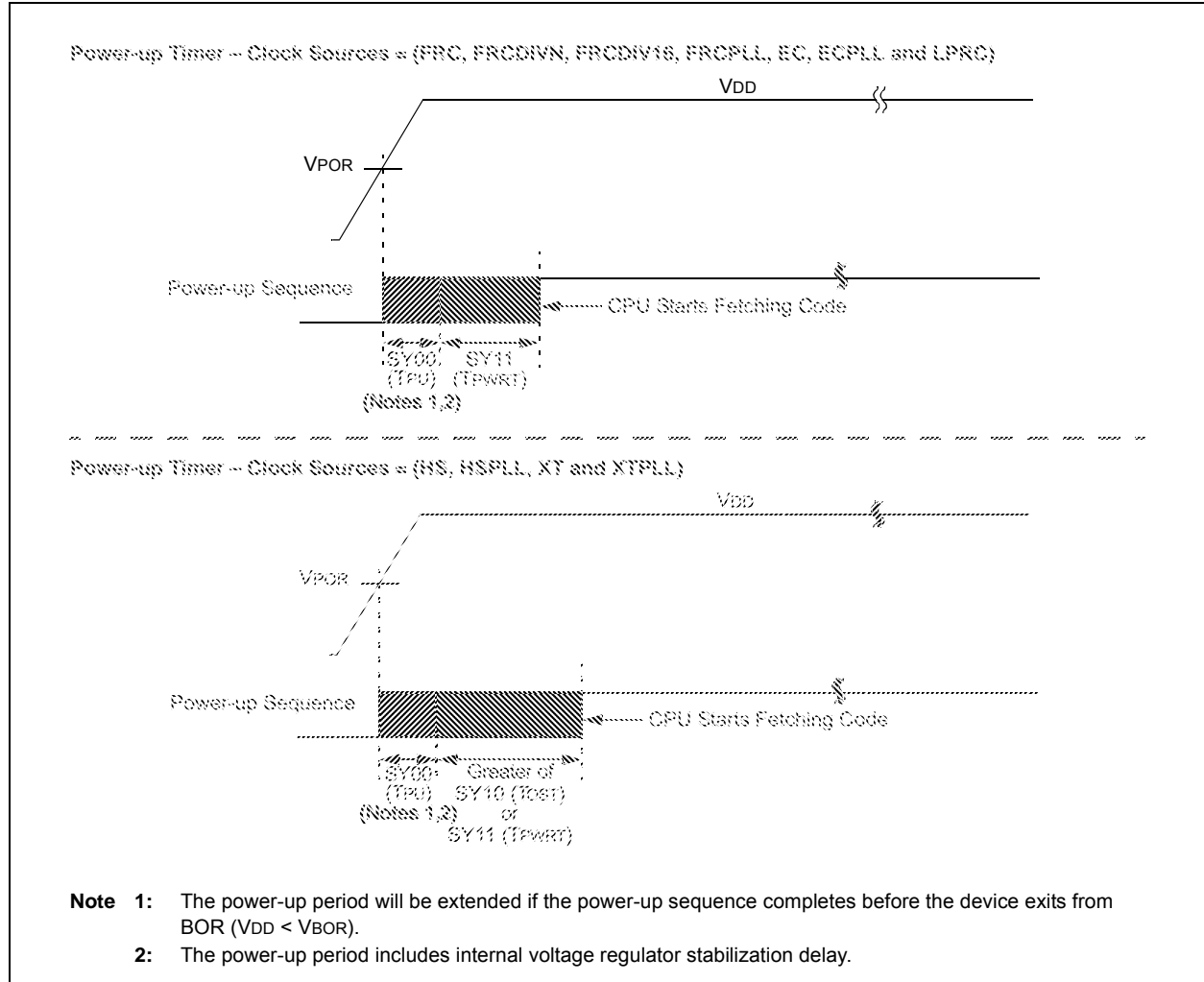
**Note 1:** Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

**2:** Instruction cycle period (Tcy) equals two times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type, under standard operating conditions, with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "Minimum" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Maximum" cycle time limit is "DC" (no clock) for all devices.

**3:** Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.

**4:** This parameter is characterized but not tested in manufacturing.

**FIGURE 30-5: POWER-ON RESET TIMING CHARACTERISTICS**



# dsPIC33EVXXXGM00X/10X FAMILY

**TABLE 30-44: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0)  
TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic <sup>(1)</sup>	Min.	Typ. <sup>(2)</sup>	Max.	Units	Conditions
SP70	FscP	Maximum SCK1 Input Frequency	—	—	25	MHz	See <b>Note 3</b>
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 and <b>Note 4</b>
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 and <b>Note 4</b>
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 and <b>Note 4</b>
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 and <b>Note 4</b>
SP35	Tsch2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	20	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	20	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	15	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1} \downarrow$ to SCK1 $\uparrow$ or SCK1 $\downarrow$ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1} \uparrow$ to SDO1 Output High-Impedance	10	—	50	ns	See <b>Note 4</b>
SP52	Tsch2ssH, TscL2ssH	$\overline{SS1} \uparrow$ after SCK1 Edge	1.5 TCY + 40	—	—	ns	See <b>Note 4</b>

**Note 1:** These parameters are characterized but not tested in manufacturing.

**2:** Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

**3:** The minimum clock period for SCK1 is 40 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

**4:** Assumes 50 pF load on all SPI1 pins.



# dsPIC33EVXXXGM00X/10X FAMILY

**TABLE 30-55: ADC MODULE SPECIFICATIONS (12-BIT MODE)**

AC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
<b>ADC Accuracy (12-Bit Mode)</b>							
AD20a	Nr	Resolution	12 data bits			bits	
AD21a	INL	Integral Nonlinearity	-2	—	+2	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V
AD22a	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V
AD23a	GERR	Gain Error	-10	4	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V
AD24a	EOFF	Offset Error	-10	1.75	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V
AD25a	—	Monotonicity <sup>(2)</sup>	—	—	—	—	Guaranteed
<b>Dynamic Performance (12-Bit Mode)</b>							
AD30a	THD	Total Harmonic Distortion	—	—	-75	dB	
AD31a	SINAD	Signal to Noise and Distortion	68.5	69.5	—	dB	
AD32a	SFDR	Spurious Free Dynamic Range	80	—	—	dB	
AD33a	FNYQ	Input Signal Bandwidth	—	—	250	kHz	
AD34a	ENOB	Effective Number of Bits	11.09	11.3	—	bits	

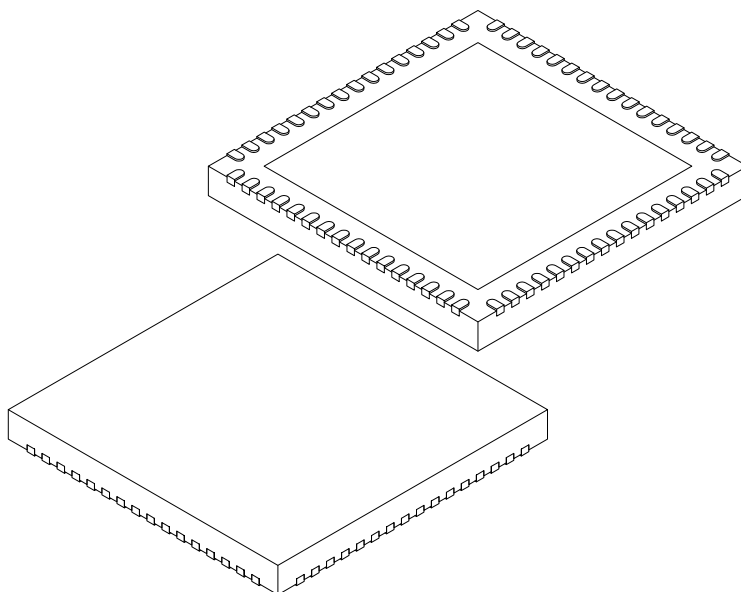
**Note 1:** Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

**2:** The conversion result never decreases with an increase in the input voltage.

# dsPIC33EVXXXGM00X/10X FAMILY

## 64-Lead Very Thin Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [VQFN] With 7.15 x 7.15 Exposed Pad [Also called QFN]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	64		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	9.00 BSC		
Exposed Pad Width	E2	7.05	7.15	7.25
Overall Length	D	9.00 BSC		
Exposed Pad Length	D2	7.05	7.15	7.25
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

### Notes:

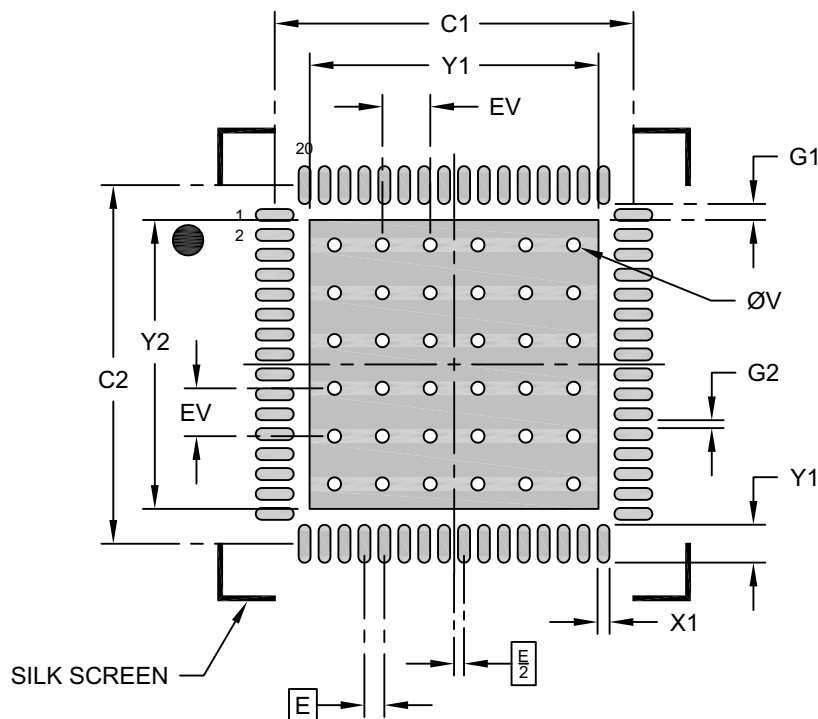
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.  
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-149D [MR] Sheet 2 of 2

# dsPIC33EVXXXGM00X/10X FAMILY

## 64-Lead Very Thin Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [VQFN] With 7.15 x 7.15 Exposed Pad [Also called QFN]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2			7.25
Optional Center Pad Length	Y2			7.25
Contact Pad Spacing	C1		9.00	
Contact Pad Spacing	C2		9.00	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			0.95
Contact Pad to Center Pad (X64)	G1	0.40		
Spacing Between Contact Pads (X60)	G2	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

**Notes:**

- Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2149C [MR]

# dsPIC33EVXXXGM00X/10X FAMILY

SENTx Module.....	238
Shared I/O Port Structure .....	143
SP1x Module.....	222
Type B Timer (Timer2 and Timer4).....	176
Type B/Type C Timer Pair (32-Bit Timer).....	177
Type C Timer (Timer3 and Timer5) .....	176
UARTx Module.....	247
User-Programmable Blanking Function .....	302
Watchdog Timer (WDT).....	325
Brown-out Reset (BOR).....	324

## C

C Compilers	
MPLAB XC .....	338
CAN	
CAN Module	
Control Registers .....	255
Message Buffers .....	275
Word 0 .....	275
Word 1 .....	275
Word 2 .....	276
Word 3 .....	276
Word 4 .....	277
Word 5 .....	277
Word 6 .....	278
Word 7 .....	278
Modes of Operation .....	254
Overview .....	253
Characteristics for High-Temperature	
Devices (+150°C).....	439
Characteristics for Industrial/Extended Temperature	
Devices (-40°C to +125°C).....	413
Charge Time Measurement Unit (CTMU) .....	279
Charge Time Measurement Unit. See CTMU.	
Code Examples	
Port Write/Read .....	144
PORTA Slew Selections .....	145
PWM1 Write-Protected Register	
Unlock Sequence.....	200
PWSAV Instruction Syntax .....	133
Code Protection .....	317, 326
CodeGuard Security.....	317, 326
Comparator Voltage Reference	
Configuring.....	313
Control Registers .....	315
Configuration Bits .....	317
Description .....	320
Controller Area Network (CAN).....	253
Controller Area Network. See CAN.	
CPU.....	21
Addressing Modes .....	21
Arithmetic Logic Unit (ALU).....	30
Control Registers .....	25
Data Space Addressing .....	21
DSP Engine .....	30
Instruction Set .....	21
Programmer's Model.....	23
CTMU	
Control Registers .....	281
Customer Change Notification Service .....	493
Customer Notification Service .....	493
Customer Support .....	493

## D

Data Address Space.....	36
Alignment.....	36
Memory Map for 256-Kbyte Devices .....	39
Memory Map for 32-Kbyte Devices .....	37
Memory Map for 64/128-Kbyte Devices .....	38
Near Data Space .....	36
SFR Space .....	36
Width .....	36
Data Space	
Extended X.....	72
Memory Arbitration, Bus Master Priority .....	73
Paged Memory Scheme .....	68
DC Characteristics.....	342
Brown-out Reset (BOR).....	349
CTMU Current Source .....	394
Doze Current (IDOZE).....	347
Filter Capacitor (CEFC) Specifications .....	343
High Temperature.....	404
Brown-out Reset (BOR).....	407
CTMU Current Source.....	410
I/O Pin Input Specifications .....	406
I/O Pin Output Specifications.....	407
Idle Current (IDLE).....	405
Op Amp/ Comparator x.....	411
Operating Current (IDD) .....	405
Operating MIPS vs. Voltage .....	404
Power-Down Current (IPD).....	405
Program Memory.....	407
Temperature and Voltage Specifications.....	404
Doze Current (IDOZE).....	405
I/O Pin Input Specifications.....	348
I/O Pin Output Specifications.....	349
Idle Current (IDLE).....	345
Internal Band Gap Reference Voltage.....	350
Op Amp/Comparator x Specifications.....	392
Op Amp/Comparator x Voltage Reference	
Specifications .....	393
Operating Current (IDD) .....	344
Operating MIPS vs. Voltage .....	342
Power-Down Current (IPD).....	346
Program Memory .....	350
Temperature and Voltage Specifications.....	343
Thermal Operating Conditions.....	342
Deadman Timer (DMT).....	181
Control Registers .....	182
Deadman Timer. See DMT.	
Development Support .....	337
Direct Memory Access. See DMA.	
DMA Controller	
Channel to Peripheral Associations.....	110
Control Registers .....	111
Supported Peripherals .....	109
DMAC Registers	
DMAxCNT.....	111
DMAxCON .....	111
DMAxPAD.....	111
DMAxREQ .....	111
DMAxSTAHL .....	111
DMAxSTBHL .....	111
DMT	
Doze Mode .....	135

---

**Note the following details of the code protection feature on Microchip devices:**

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

---

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

*Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELoq® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.*

**QUALITY MANAGEMENT SYSTEM**  
**CERTIFIED BY DNV**  
**== ISO/TS 16949 ==**

### Trademarks

The Microchip name and logo, the Microchip logo, AnyRate, dsPIC, FlashFlex, flexPWR, Heldo, JukeBlox, KeeLoq, KeeLoq logo, Klear, LANCheck, LINK MD, MediaLB, MOST, MOST logo, MPLAB, OptoLyzer, PIC, PICSTART, PIC32 logo, RightTouch, SpyNIC, SST, SST Logo, SuperFlash and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

ClockWorks, The Embedded Control Solutions Company, ETHERSYNCH, Hyper Speed Control, HyperLight Load, IntelliMOS, mTouch, Precision Edge, and QUIET-WIRE are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, BodyCom, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, EtherGREEN, In-Circuit Serial Programming, ICSP, Inter-Chip Connectivity, JitterBlocker, KlearNet, KlearNet logo, MiWi, motorBench, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, PureSilicon, RightTouch logo, REAL ICE, Ripple Blocker, Serial Quad I/O, SQL, SuperSwitcher, SuperSwitcher II, Total Endurance, TSHARC, USBCheck, VariSense, ViewSpan, WiperLock, Wireless DNA, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

GestIC is a registered trademarks of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2013-2016, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

ISBN: 978-1-5224-0975-5